

REMARKS

In paragraph 2 of the Office Action, claims 1-4, 7-15, 18-26, 29-37, 40-48, 51-59, ~~62-70~~, 73-81, 83-88 and 97 were rejected under 35 U.S.C. §102(b) as being anticipated by Egan.

Reconsideration is requested in view of this Amendment.

Claims 1, 12, 23, 34, 45, 56, 67, 7 and 97, which are the independent claims, have been amended to point out that the surface is selectively modified in a predetermined pattern by applying no surface treatment in some areas and surface treatment in other areas. This language is based on the original specification at page 28, line 3-10. The Egan patent has been cited as disclosing an article of manufacture (figure 6-comprising a first support layer of film with a permanent bond interface, a second film layer adhesively secured to the lower surface of the first film at the permanent adhesive bond but having a separable interface between the adhesive and the release coat of film with a removable die cut segment having a variable selective adhesion to the separable interface. The Egan construction provides releasable layers that have constant adhesion and not variable adhesion that is provided with some areas treated and other areas not treated. The total treatment method Egan makes it difficult to raise an edge in order to begin to remove the removable portion.

The applicant wishes to point out that the Egan construction requires that a portion of the lamination can be removed by separating two releasably joined plastic sheets without any adhesive being exposed on either the removed member or the surface from which the removed member was removed (col. 2, lines 39-42).

Claim 1 of the present application points out that there is between a first film layer and a second film layer, a permanent bond interface A. In addition, a third film

layer is laminated onto the upper surface of the first film layer and the device has a removable segment that is formed by die cutting through the third and first layers. The die cut segment has on its lower surface a pattern of selective variable adhesion which is achieved by variable surface treatment of the lower surface of the first layer or the upper surface of the second layer or by the surface treatment of both the first and the second layers. This construction allows for the separation of the upper and lower structures due to the presence of the pattern of selective variable adhesion which has areas that are treated and areas that are not treated. Egan does not disclose the concept of selective variable surface treatment as a technique for modifying the adhesion at an interface which is at one side of an adhesive while the interface at the opposite side of the adhesive layer is not modified. For these reasons, it is requested that this ground of rejection be withdrawn.

In paragraph 3 of the Office Action, claims 5-6, 16-17, 27-28, 39-40, 49-50, 60-61, 71-72 and 82-83 were rejected under 35 U.S.C. §103(a) as being unpatentable over Egan in view of Kobe.

Reconsideration is requested.

The Egan reference has been distinguished above based on the absence of a selective variable adhesion that is achieved by the application of a treatment in some area while leaving other areas untreated.

The Kobe patent at col. 18, line 24, mentions the use of flame treatment to increase the dyne level or adhesion. However, the concept of selective flame treatment is not disclosed by Kobe. For this reason and the reasons set forth above, the prior art does not make obvious the treatment of some areas and no treatment of other areas. For these reasons, it is requested that this ground of rejection be withdrawn.

In paragraph 5 of the Office Action, claims 89-96 were rejected under 35 U.S.C. §103(a) as being unpatentable over Egan in view of Grabau.

Reconsideration is requested.

The deficiencies of the Egan reference have been discussed above. Egan only teaches thermal lamination of two plastic films where a pattern of a release coating has been applied to one of the plastic sheets prior to the thermal lamination step for the purpose of allowing the separation of the thermally bonded sheets.

The Grabau patent discloses the concept of embedding an RFID device into a label. It does not disclose the concept of providing one type of interface between one face of an adhesive layer and a different interface between the opposite face of the adhesive layer. The Egan patent has been distinguished above from the claims of the present application and nothing in Grabau provides any information that suggests the particular structure that is pointed out in the amended claims of the present application. For these reasons, it is requested that this ground of rejection be withdrawn.

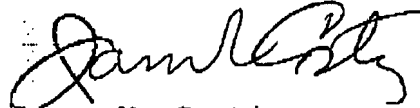
In paragraph 5 of the Office action, claims 1-97 were rejected for obviousness double patenting over claims 1-53 of copending application 10/505,392.

Reconsideration is requested.

Since this is a provisional rejection because no claims have been allowed in the copending application, it is requested that this ground of rejection be held in abeyance pending the allowance of copending application Serial No. 10/505,392.

An early and favorable action is earnestly solicited.

Respectfully submitted,



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